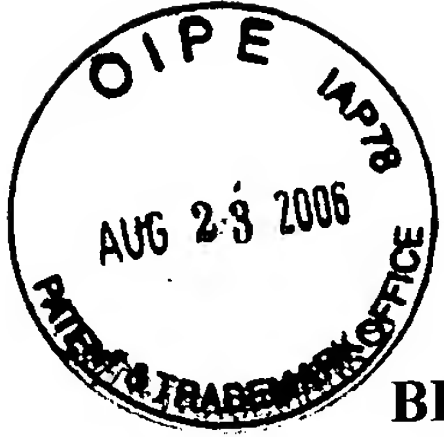


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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES**

In re Application of:

Hill et al.

Serial No.: 10/067,410

Filed: February 4, 2002

For: METHOD FOR FORMING A
SELECTIVE CONTACT AND LOCAL
INTERCONNECT IN SITU (as amended)

Confirmation No.: 8302

Examiner: H. Lee

Group Art Unit: 2823

Attorney Docket No.: 2269-3380.1US

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APPEAL BRIEF

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Attn: Board of Patent Appeals and Interferences

Sir:

This APPEAL BRIEF is being submitted in the format required by 37 C.F.R.

§ 41.37(c)(1), with the fee required by 37 C.F.R. § 41.20(b)(2).

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(I) REAL PARTY IN INTEREST

U.S. Application Serial No. 10/067,410 (hereinafter “the ‘410 Application”), the application at issue in the above-referenced appeal, has been assigned to Micron Technology, Inc., as evidenced by the assignment that has been recorded with the U.S. Patent & Trademark Office (hereinafter “the Office”) at Reel No. 9119, Frame No. 0645. Accordingly, Micron Technology, Inc., is the real party in interest in the above-referenced appeal.

(II) RELATED APPEALS AND INTERFERENCES

There are no related appeals, interferences, or other actions of which appellants or their attorneys are aware that may have a bearing on the outcome of the decision of the Board of Patent Appeals and Interferences (hereinafter “the Board”) in the above-referenced appeal.

(III) STATUS OF CLAIMS

There are currently twenty-eight (28) claims pending and under consideration in the ‘410 Application. All twenty-eight claims stand finally rejected. The final rejections of claims 1-28 are being appealed.

(IV) STATUS OF AMENDMENTS

The most recent claim amendments the ‘410 Application were introduced in an Amendment under 37 C.F.R. § 1.116 that was filed on October 20, 2004.

Three Office Actions were issued following the Amendment of October 20, 2004, with each rejection based upon the same art. Despite numerous explanations as to the patentability of

claims 1-28, substantially the same the same rejections were presented in the final Office Action of April 3, 2006, in which the Examiner merely withdrew his reliance upon one reference (U.S. Patent 6,699,530 to Danek et al.) from each of the previously presented rejections. Those rejections were maintained in an Advisory Action dated June 16, 2006.

Accordingly, a Notice of Appeal was filed in the '410 Application on June 23, 2006, and is followed by this Appeal Brief, which is being submitted within two months of the date on which the Notice of Appeal was filed.

No amendments have been presented in the '410 Application since the final Office Action of April 3, 2006, was issued.

(V) SUMMARY OF CLAIMED SUBJECT MATTER

Independent claim 1 of the '410 Application is directed to a method that includes selective deposition of metal silicide and the subsequent, in situ, deposition of an interconnect material. *See, e.g.*, paragraph [0013]. The method of independent claim 20 of the '410 Application includes selective deposition of a contact material and the subsequent, in situ, deposition of an interconnect material. *See, e.g.*, paragraph [0013]. Without limiting the scopes of the claims, the metal silicide or contact material may include, but is not limited to titanium silicide, tungsten silicide, molybdenum silicide, and/or platinum silicide (paragraph [0027]), while the interconnect material may include, without limitation, titanium nitride (paragraph [0034]).

(VI) GROUND OF REJECTION TO BE REVIEWED ON APPEAL

(A) The 35 U.S.C. § 103(a) rejections of claims 1, 8-10, 12-14, 18-20, 23, and 25-28 for reciting subject matter which is assertedly unpatentable over the subject matter taught in U.S. Patent 6,020,259 to Chen et al. (hereinafter “Chen”);

(B) The rejections of claims 2-5 and 21-22 under 35 U.S.C. § 103(a) for being drawn to subject matter that is allegedly unpatentable over that taught in Chen, in view of teachings from U.S. Patent 5,043,299 to Chang et al. (hereinafter “Chang”);

(C) The rejections of claims 6 and 7 under 35 U.S.C. § 103(a) for being directed to subject matter that is allegedly unpatentable over teachings from Chen, in view of the teachings of U.S. Patent 5,162,259 to Kolar et al. (hereinafter “Kolar”);

(D) The 35 U.S.C. § 103(a) rejections of claims 11 and 24 for being drawn to subject matter which is purportedly unpatentable over the subject matter taught in Chen, in view of teachings from U.S. Patent 5,821,164 to Kim et al. (hereinafter “Kim”); and

(E) The rejections of claims 15-17 under 35 U.S.C. § 103(a) for reciting subject matter that is allegedly unpatentable over the subject matter taught in Chen, in view of teachings from U.S. Patent 6,001,729 to Shinriki et al. (hereinafter “Shinriki”).

(VII) ARGUMENT

Claims 1-28 have been finally rejected under 35 U.S.C. § 103(a).

(A) LEGAL AUTHORITY

The standard for establishing, maintaining, and upholding a rejection under 35 U.S.C. § 103(a) is set forth in M.P.E.P. § 706.02(j), which provides:

To establish a *prima facie* case of obviousness, three basic criteria must be met. First, there must be some suggestion or motivation, either in the references themselves or in the knowledge generally available to one of ordinary skill in the art, to modify the reference or combine reference teachings. Second, there must be a reasonable expectation of success. Finally, the prior art reference (or references when combined) must teach or suggest all the claim limitations. The teaching or suggestion to make the claimed combination and the reasonable expectation of success must both be found in the prior art, and not based on applicant's disclosure. *In re Vaeck*, 947 F.2d 488, 20 USPQ2d 1438 (Fed. Cir. 1991).

The burden is on the Office to demonstrate that a reference teaching is inherent. M.P.E.P. § 2112. The following guidance has been provided by M.P.E.P. § 2112 in determining whether or not this burden has been met:

The fact that a certain result or characteristic may occur or be present in the prior art is not sufficient to establish inherency of that result or characteristic. *In re Rijckaert*, 9 F.3d 1531, 1534, 28 USPQ2d 1955, 1957 (Fed. Cir. 1993) . . . 'To establish inherency, the extrinsic evidence 'must make clear that the missing descriptive matter is necessarily present in the thing described in the reference, and that it would be so recognized by persons of ordinary skill . . . ' *In re Robertson*, 169 F.3d 743, 745, 49 USPQ2d 1949, 1950-51 (Fed. Cir. 1991).

(B) REFERENCES RELIED UPON

Chen

Chen teaches a process that includes selectively depositing titanium silicide on a surface of a silicon substrate that is exposed through a contact opening, then blanket depositing titanium

nitride over the interconnect. Col. 3, lines 2-26. Chen does not include any teaching or suggestion that these deposition processes may be effected *in situ*.

Chang

Chang is relied upon for its teachings that relate to exposing doped areas of semiconductor device structures to a plasma including activated species of nitrogen or hydrogen. Final Office Action, page 4.

Kolar

Kolar is relied upon for its teaching that metal silicide layers may, prior to depositing interconnect materials thereover, be cleaned with hydrochloric acid. Final Office Action, page 5.

Kim

Kim teaches that titanium nitride may be selectively deposited in to contact holes. Final Office Action, page 6. Kim asserts that a conductive layer 16, which may be formed from a material such as aluminum, copper, titanium, or titanium nitride, may be “selectively deposited on the exposed surface of [an] interlevel layer 14a[,] including [a] contact hole 15[therethrough].” Col. 4, lines 24-27. FIG. 2f of Kim, however, shows that the interlevel layer 14a covers the entire substrate 11, and that the entire upper surface of interlevel layer 14 appears to be exposed. Moreover, the formation of conductive layer 16 must be followed by an etch-back, as explained at col. 4, lines 28-31 of Kim, to remove conductive material from the

upper surface of the interlevel layer 14a and, thus, to define conductive lines 16 within the contact holes 15.

Shinriki

Shinriki teaches that titanium silicide may be selectively deposited by reacting a metallic precursor with a silicon compound. Final Office Action, page 6.

(C) ANALYSIS

(1) CHEN

Claims 1, 8-10, 12-14, 18-20, 23, and 25-28 stand rejected under 35 U.S.C. § 103(a) for reciting subject matter which is assertedly unpatentable over the subject matter taught in Chen.

It has been asserted that Chen's use of the term "subsequent" in describing the order of titanium silicide and titanium nitride deposition processes and the fact that Chen teaches that both processes may be effected by chemical vapor deposition (CVD) implies and inherently teaches that the processes are conducted in the same chamber, or *in situ* with one another. Final Office Action, pages 2 & 3. Notably, a teaching is inherent only if it is necessary.

M.P.E.P. § 2112. In fact, the term "subsequent" in Chen does not imply anything other than the fact that the titanium silicide deposition process is followed by the titanium nitride deposition process. Without actually teaching or suggesting that the two processes of Chen are effected in the same chamber, or *in situ*, one cannot imply anything more from the disclosure of Chen. This is particularly true since one of ordinary skill in the art would readily understand that the titanium

silicide deposition process disclosed in Chen could be effected in a different chamber from the titanium nitride deposition process disclosed in Chen.

Therefore, it is respectfully submitted that Examiner has not met his burden of demonstrating that the process of Chen inherently includes the deposition of both titanium silicide and titanium nitride *in situ* with one another.

In view of the foregoing, it is respectfully submitted that there are at least two reasons that the teachings of Chen do not support a *prima facie* case of obviousness against any of claims 1, 8-10, 12-14, 18-20, 23, or 25-28.

(a) NO MOTIVATION TO COMBINE

First, it is respectfully submitted that, without the benefit of hindsight that the claims of the above-referenced application have provided to the Examiner, one of ordinary skill in the art wouldn't have been motivated to modify teachings from Chen in the manner that has been asserted. It has been asserted that, since Chen teaches a process in which a metal silicide and an interconnect material may be deposited and that both of these materials may be deposited by the same process (*i.e.*, chemical vapor deposition (CVD)), that it would have been obvious to one of ordinary skill in the art to effect these deposition process *in situ* with one another. If it would have been obvious to conduct deposition processes that require at least one different reactant *in situ* with one another, then there surely would have been some disclosure to that effect in the prior art. Unfortunately, there is none.

Notably, the teachings of Chen are limited to introducing single sets of reactants into a chamber while a semiconductor substrate resides therein. More specifically, in Chen, a first set

of reactants, which are necessary for depositing titanium silicide, are introduced into a chamber with a substrate therein. Col. 3, lines 2-19. Without teaching or suggesting that the semiconductor substrate may remain in the chamber in which the titanium silicide deposition occurred, Chen teaches that titanium nitride is deposited onto the semiconductor substrate as another, second set of reactants chemically react with each other.

Therefore, Chen includes no teaching or suggestion that could have motivated one of ordinary skill in the art to modify its teachings in such a way as to effect to different deposition processes *in situ* with one another.

(b) CHEN DOES NOT TEACH OR SUGGEST EACH AND EVERY CLAIM ELEMENT

Second, Chen does not teach or suggest each and every element of any of claims 1, 8-10, 12-14, 18-20, 23, or 25-28.

Chen lacks any teaching or suggestion of “depositing an interconnect material onto . . . metal silicide after and in situ with causing [a] chemical reaction” “to selectively deposit metal silicide” on the “surface of at least one exposed, doped area of [a] semiconductor device structure,” as required by independent claim 1. Nor does Chen teach or suggest “depositing an interconnect material onto [a] contact material after and in situ with causing [a] chemical reaction” “to selectively deposit [the] contact material” on an “exposed active device region of [a] semiconductor device structure,” as required by independent claim 20.

In this regard, Chen merely teaches that “a blanket chemical vapor deposition is carried out . . . to form a TiN layer” subsequent to the selective deposition of a TiSi_2 layer. Col. 3, lines 20-23.

As a *prima facie* case of obviousness has not been established against independent claim 1 or independent claim 20, it is respectfully submitted that these claims are allowable under 35 U.S.C. § 103(a).

Claims 8-10, 12-14, 18, and 19 are each allowable, among other reasons, for depending directly or indirectly from claim 1, which is allowable.

Each of claims 23 and 25-28 is allowable, among other reasons, for depending directly or indirectly from claim 20, which is allowable.

(2) CHEN IN VIEW OF CHANG

Claims 2-5 and 21-22 have been rejected under 35 U.S.C. § 103(a) for being drawn to subject matter that is allegedly unpatentable over teachings from Chen, in view of the teachings of Chang.

Claims 2-5 are each allowable, among other reasons, for depending directly or indirectly from claim 1, which is allowable.

Claims 21 and 22 are both allowable, among other reasons, for depending directly and indirectly, respectively, from claim 20, which is allowable.

Claim 22 is further allowable since neither Chen nor Chang, taken together or separately, teaches or suggests exposing a semiconductor device structure to a nitrogen-ammonia plasma.

While the Examiner has asserted, at page 5 of the Final Office Action, that use of a

nitrogen-ammonia plasma would be obvious depending upon the type of material to be cleaned, the Examiner has not shown any art that discloses use of such a plasma.

(3) CHEN IN VIEW OF KOLAR

Claims 6 and 7 stand rejected under 35 U.S.C. § 103(a) for reciting subject matter which is purportedly unpatentable over the teachings of Chen, in view of teachings from U.S. Patent 5,162,259 to Kolar et al.

Claims 6 and 7 are both allowable, among other reasons, for depending directly and indirectly, respectively, from claim 1, which is allowable.

(4) CHEN IN VIEW OF KIM

Claims 11 and 24 stand rejected under 35 U.S.C. § 103(a) for reciting subject matter which is assertedly unpatentable over that taught in Chen et al., in view of teachings from U.S. Patent 5,821,164 to Kim et al. (hereinafter "Kim").

Claim 11 is allowable, among other reasons, for depending directly from claim 1, which is allowable.

Claim 24 is allowable, among other reasons, for depending directly from claim 20, which is allowable.

Furthermore, a *prima facie* case of obviousness has not been established against either claim 11 or claim 24. Kim has been relied upon for purportedly teaching that an interconnect material may be selectively deposited. Kim even asserts that a conductive layer 16, which may be formed from a material such as aluminum, copper, titanium, or titanium nitride, may be

“selectively deposited on the exposed surface of [an] interlevel layer 14a[,] including [a] contact hole 15[therethrough].” Col. 4, lines 24-27. From FIG. 2f of Kim, however, it appears that the interlevel layer 14a covers the entire substrate 11, and that the entire upper surface of interlevel layer 14 appears to be exposed. Moreover, the formation of conductive layer 16 must be followed by an etch-back, as explained at col. 4, lines 28-31 of Kim, to remove conductive material from the upper surface of the interlevel layer 14a and, thus, to define conductive lines 16 within the contact holes 15. Thus, deposition of the conductive layer 16 would certainly not be selective.

Chen also lacks any teaching or suggestion of selectively depositing an interconnect material.

As claims 11 and 24 both require that an interconnect material be selectively deposited, according to the ordinary meaning of that term, as used in the art, the teachings of Kim cannot be combined with teachings from Chen in such a way as to establish a *prima facie* case of obviousness against either of these claims.

(5) CHEN IN VIEW OF SHINRIKI

Claims 15-17 stand rejected under 35 U.S.C. § 103(a) for reciting subject matter which is allegedly unpatentable over the subject matter taught in Chen, in view of teachings from U.S. Patent 6,001,729 to Shinriki et al.

Claims 15-17 are each allowable, among other reasons, for depending directly or indirectly from claim 1, which is allowable.

(VIII) CLAIMS APPENDIX

The current status of each claim that has been introduced into the '799 Application is set forth in CLAIMS APPENDIX to this Appeal Brief.

(IX) EVIDENCE APPENDIX

No evidence has been submitted pursuant to 37 C.F.R. §§ 1.130, 1.131, or 1.132. Accordingly, no evidence appendix accompanies this Appeal Brief.

(X) RELATED PROCEEDINGS APPENDIX

No decisions have been rendered by the Board or any court in a related application. Therefore, this Appeal Brief is not accompanied by a related proceedings appendix.

(XI) CONCLUSION

It is respectfully submitted that:

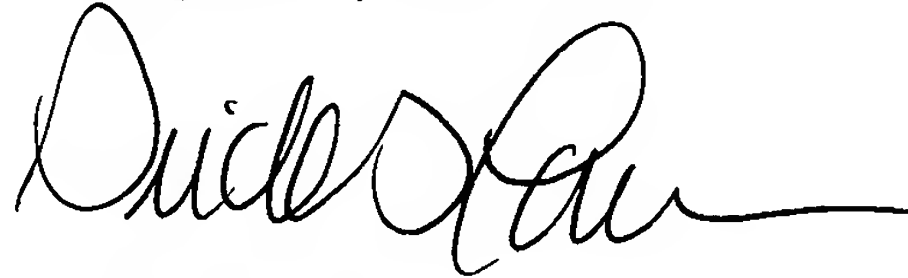
- (A) Claims 1, 8-10, 12-14, 18-20, 23, and 25-28 are allowable under 35 U.S.C. § 103(a) for reciting subject matter which is patentable over the subject matter taught in Chen;
- (B) Claims 2-5 and 21-22 are allowable under 35 U.S.C. § 103(a) for being drawn to subject matter that is patentable over that taught in Chen, in view of teachings from Chang;
- (C) Claims 6 and 7 are allowable under 35 U.S.C. § 103(a) for being directed to subject matter that is patentable over teachings from Chen, in view of the teachings of Kolar;

(D) Claims 11 and 24 are allowable under 35 U.S.C. § 103(a) for being drawn to subject matter which is patentable over the subject matter taught in Chen, in view of teachings from Kim; and

(E) Claims 15-17 are allowable under 35 U.S.C. § 103(a) for reciting subject matter that is patentable over the subject matter taught in Chen, in view of teachings from Shinriki.

Accordingly, it is respectfully requested that the 35 U.S.C. § 103(a) rejections of claims 1-28 be reversed, and that each of these claims be allowed.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brick G. Power", with a long horizontal flourish extending to the right.

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Date: August 23, 2006
BGP/eg
Document in ProLaw

CLAIMS APPENDIX

1. A method for fabricating an interconnect adjacent a contact of a semiconductor device structure, comprising:
causing a chemical reaction adjacent to a surface of at least one exposed, doped area of the semiconductor device structure to selectively deposit metal silicide thereon without reacting material of the at least one exposed, doped area ; and
depositing an interconnect material onto the metal silicide after and in situ with causing the chemical reaction.
2. The method of claim 1, further comprising exposing the at least one exposed, doped area of the semiconductor device structure to a plasma.
3. The method of claim 2, wherein exposing comprises exposing the at least one exposed, doped area of the semiconductor device structure to a plasma comprising an activated species of at least one of nitrogen, hydrogen, and ammonia.
4. The method of claim 1, further comprising cleaning the semiconductor device structure.
5. The method of claim 4, wherein cleaning includes employing a cleaning agent comprising at least one of chlorine, hydrochloric acid, and hydrofluoric acid.

6. The method of claim 1, further comprising cleaning the semiconductor device structure after depositing said metal silicide.

7. The method of claim 6, wherein cleaning includes employing a cleaning agent comprising at least one of chlorine, hydrochloric acid, and hydrofluoric acid.

8. The method of claim 1, wherein causing the chemical reaction results in deposition of titanium silicide.

9. The method of claim 1, wherein depositing the interconnect material comprises blanket depositing the interconnect material.

10. The method of claim 9, further comprising patterning the interconnect material.

11. The method of claim 1, wherein depositing the interconnect material comprises selectively depositing the interconnect material.

12. The method of claim 1, further comprising depositing a layer comprising electrically conductive material over the interconnect material.

13. The method of claim 12, further comprising patterning the layer.

14. The method of claim 1, wherein depositing the interconnect material comprises depositing at least one of titanium and titanium nitride.
15. The method of claim 1, wherein causing the chemical reaction comprises reacting a metallic precursor with a silicon-containing compound.
16. The method of claim 15, wherein reacting comprises reacting a metallic precursor comprising at least one of a titanium tetrahalide, a subhalide, and a $\text{Ti}(\text{NR}_2)_4$, where R is selected from the group consisting of hydrogen and alkyl groups, with the silicon-containing compound.
17. The method of claim 15, wherein reacting comprises reacting the metallic precursor with a silicon-containing compound comprising at least one of a silane, a dichlorosilane, and a $\text{Si}_n\text{H}_{2n+2}$, where n is an integer equal to zero or more.
18. The method of claim 1, wherein depositing the interconnect material comprises reacting a metallic precursor with a reactant comprising at least one of ammonia, nitrogen trifluoride, an organic silane reactive gas, and an activated species.
19. The method of claim 18, wherein reacting comprises reacting a metallic precursor comprising at least one of a titanium tetrahalide and a $\text{Ti}(\text{NR}_2)_4$, where R is selected from the group consisting of hydrogen and alkyl groups, with the reactant.

20. A method for fabricating a selective contact and a local interconnect on a semiconductor device structure, comprising:
causing a chemical reaction adjacent to an exposed active device region of the semiconductor device structure to selectively deposit a contact material thereon without reacting a material of the active device region; and
depositing an interconnect material onto the contact material after and in situ with causing the chemical reaction.

21. The method of claim 20, further comprising exposing the semiconductor device structure to a plasma.

22. The method of claim 21, wherein exposing comprises exposing the semiconductor device structure to a nitrogen-ammonia plasma.

23. The method of claim 20, further comprising depositing an electrically conductive material onto the interconnect material.

24. The method of claim 20, wherein depositing the interconnect material comprises selectively depositing the interconnect material.

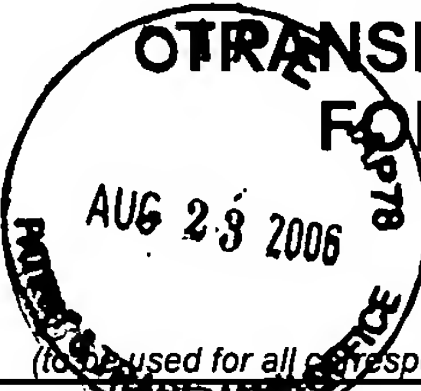
25. The method of claim 20, wherein depositing the interconnect material comprises blanket depositing the interconnect material.

26. The method of claim 25, further comprising patterning the interconnect material to form at least one interconnect therefrom over the contact material.

27. The method of claim 20, wherein causing the chemical reaction comprises depositing a selective contact material.

28. The method of claim 27, wherein depositing the selective contact material comprises depositing a metal silicide.

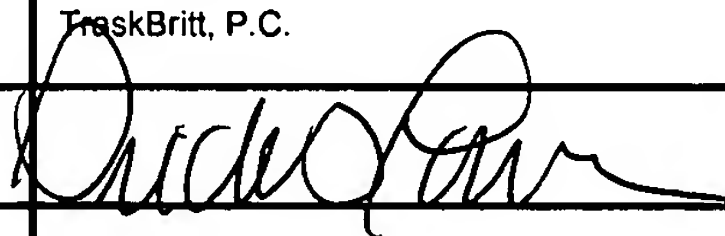
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	Application Number	10/067,410
	Filing Date	February 4, 2002
	First Named Inventor	Hill et al.
	Art Unit	2823
	Examiner Name	H. Lee
Total Number of Pages in This Submission	Attorney Docket Number 2269-3380.1US (97-0842.01/US)	

ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form <input type="checkbox"/> Fee Attached <input type="checkbox"/> Amendment / Reply <input type="checkbox"/> After Final <input type="checkbox"/> Affidavits/declaration(s) <input type="checkbox"/> Extension of Time Request <input type="checkbox"/> Express Abandonment Request <input type="checkbox"/> Information Disclosure Statement <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Reply to Missing Parts/ Incomplete Application <input type="checkbox"/> Reply to Missing Parts under 37 CFR 1.52 or 1.53	<input type="checkbox"/> Drawing(s) <input type="checkbox"/> Licensing-related Papers <input type="checkbox"/> Petition <input type="checkbox"/> Petition to Convert to a Provisional Application <input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Request for Refund <input type="checkbox"/> CD, Number of CD(s) ____ <input type="checkbox"/> Landscape Table on CD	<input type="checkbox"/> After Allowance Communication to TC <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences <input checked="" type="checkbox"/> Appeal Brief; Claims Appendix; Check no. 10042 in the amount of \$500.00 <input type="checkbox"/> Proprietary Information <input type="checkbox"/> Status Letter <input type="checkbox"/> Other Enclosure(s) (please identify below):
Remarks The Commissioner is authorized to charge any additional fees required but not submitted with any document or request requiring fee payment under 37 C.F.R. §§ 1.16 and 1.17 to Deposit Account 20-1469 during pendency of this application.		

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm	TraskBritt, P.C.		
Signature			
Printed Name	Brick G. Power		
Date	August 23, 2006	Reg. No.	38,581

CERTIFICATE OF MAILING

Express Mail Label Number: <u>EV827470225US</u>
Date of Deposit: <u>August 23, 2006</u>
Person Making Deposit: <u>Brett Hooke</u>

This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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